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HOSTAFORM® S 9243 XAP®2 ECO-B
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POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than unmodified acetal copolymer. Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness)
Preliminary Datasheet
ECO-B: Hostaform ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

Product information

Resin Identification	POM-I		ISO 1043
Part Marking Code	>POM-I<		ISO 11469

Rheological properties

Melt volume-flow rate	4	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	1950	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	44	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	40	%	ISO 527-1/-2
Flexural modulus	1850	MPa	ISO 178
Tensile creep modulus, 1h	1700	MPa	ISO 899-1
Tensile creep modulus, 1000h	950	MPa	ISO 899-1
Charpy impact strength, 23°C	N	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	200	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	15	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	9	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.45		

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	75	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	3.8		IEC 62631-2-1
Relative permittivity, 1MHz	3.8		IEC 62631-2-1
Dissipation factor, 100Hz	30	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	60	E-4	IEC 62631-2-1
Volume resistivity	1E11	Ohm.m	IEC 62631-3-1
Surface resistivity	1E13	Ohm	IEC 62631-3-2
Comparative tracking index	600		IEC 60112

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	1	%	Sim. to ISO 62
Density	1330	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	195	°C
Min. melt temperature	190	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	70	°C
Min. mould temperature	60	°C
Max. mould temperature	80	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	High impact or impact modified
Sustainability	Bio-Content

Additional information

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Storage

The product can then be stored in standard conditions until processed.

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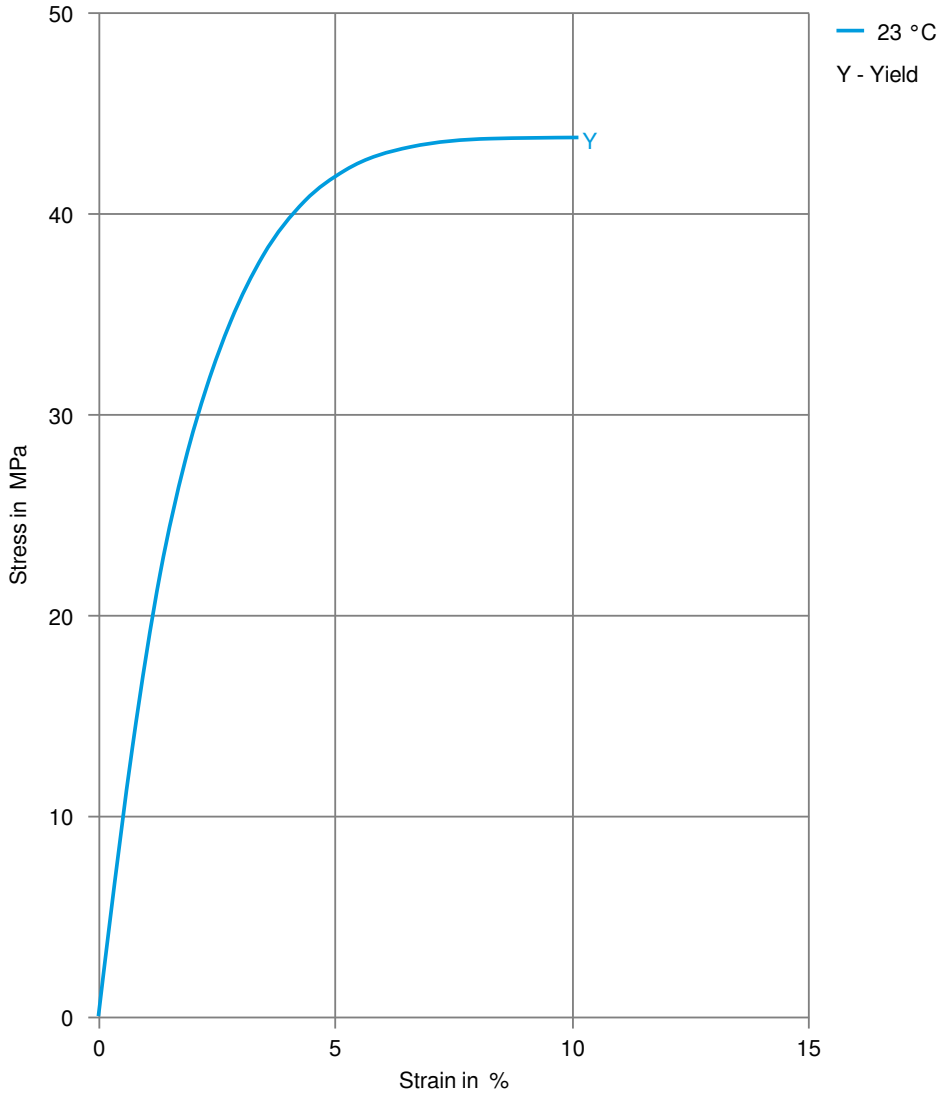
Stress-strain



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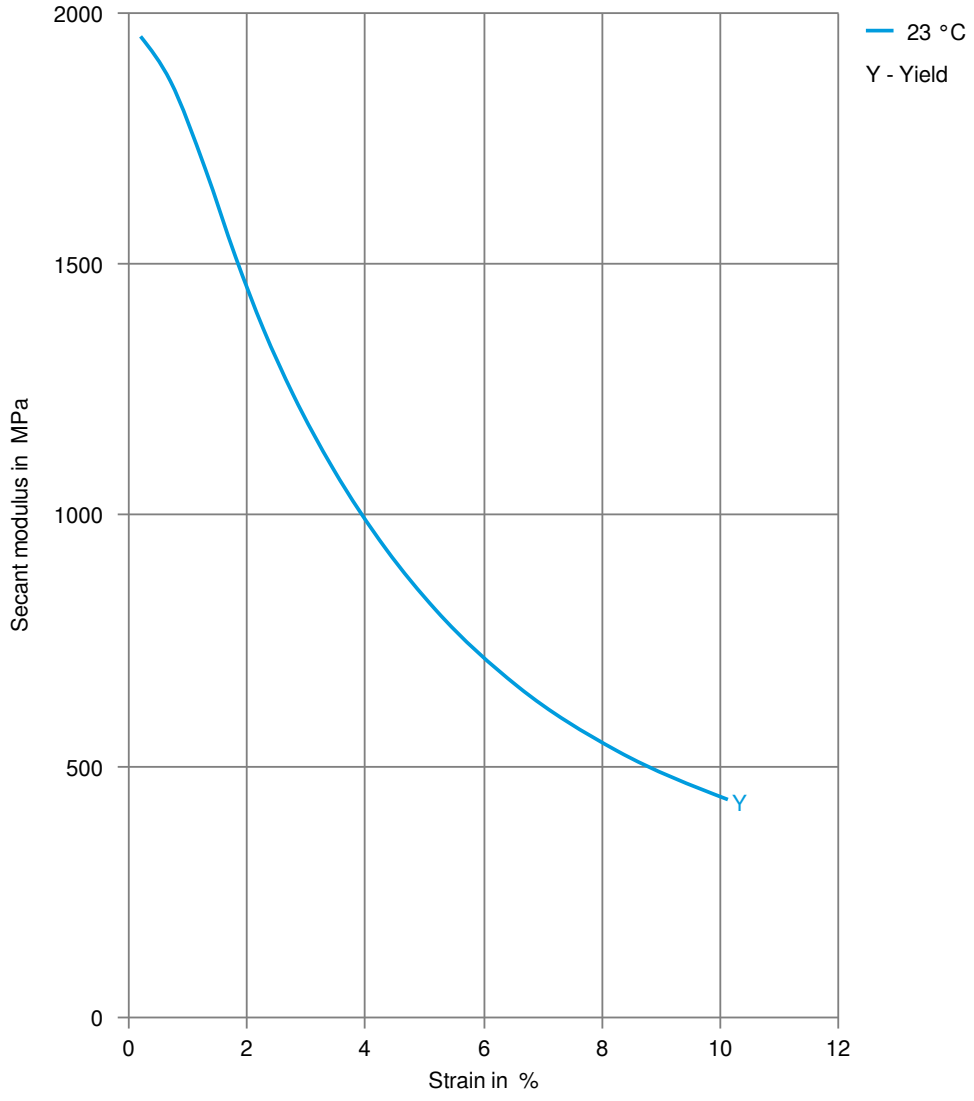
Secant modulus-strain



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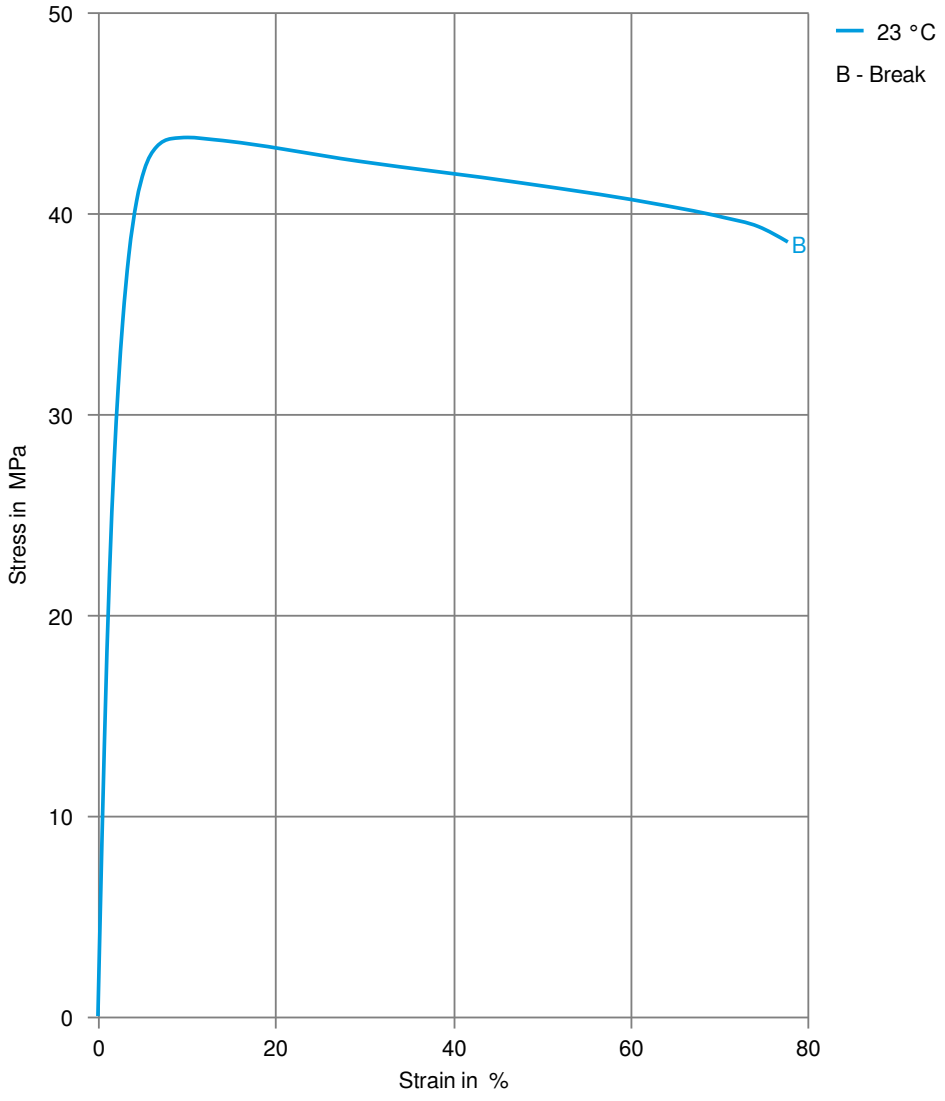
Stress-strain, 50mm/min



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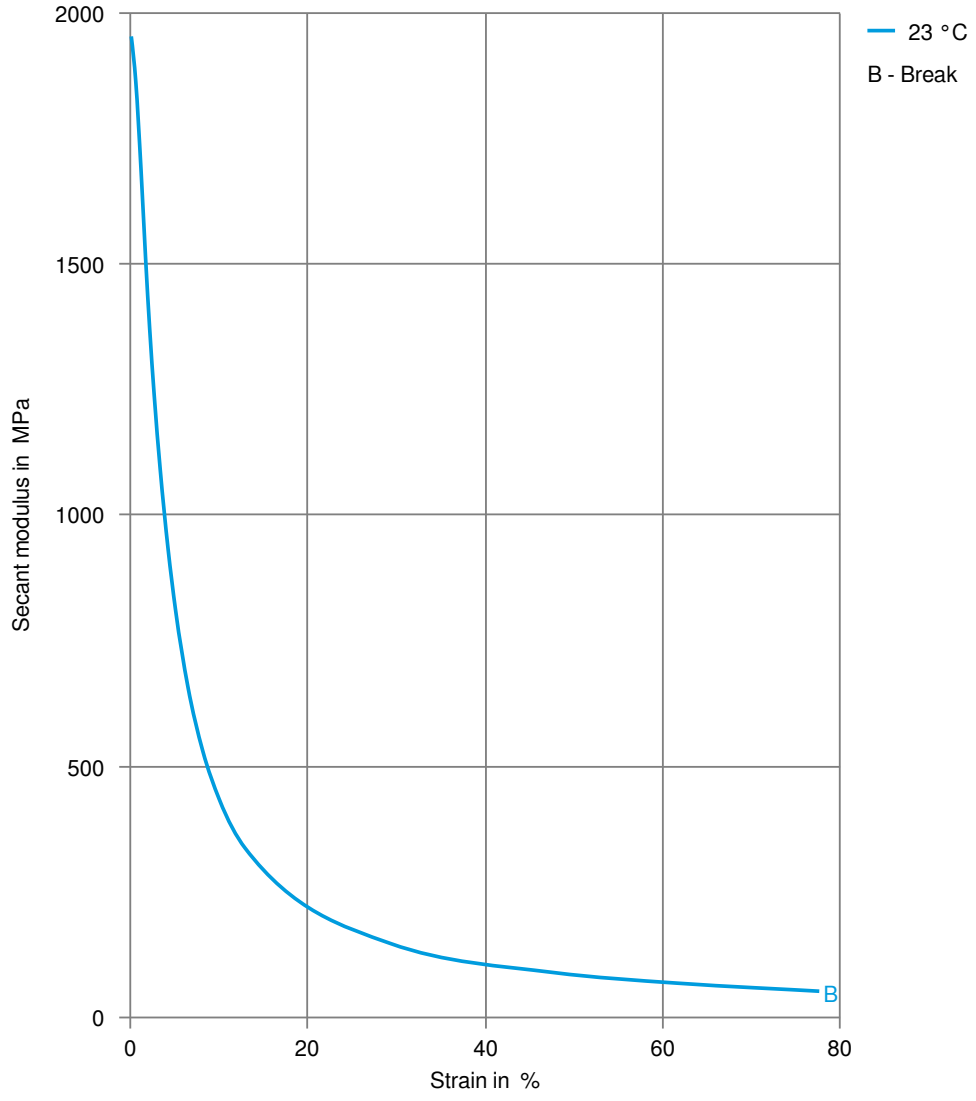
Secant modulus-strain, 50mm/min



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